

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	103	374/131.ccls. and thick\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/09 12:35
L2	172	374/141.ccls. and thick\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/09 09:50
L3	182	374/121.ccls. and thick\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/09 09:44
L4	141	374/45.ccls. and thick\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/09 09:44
L6	1563	((chemical adj (mechanical adj (polish\$4 or planar\$))) or "CMP") and (measur\$ NEAR thickness)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/09 09:53
L7	53922	((chemical adj (mechanical adj (polish\$4 or planar\$))) or "CMP")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/09 09:53
L8	16438	((chemical adj (mechanical adj (polish\$4 or planar\$))) or "CMP") and heat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/09 09:53
L9	367	((chemical adj (mechanical adj (polish\$4 or planar\$))) or "CMP") and (heat\$3 NEAR3 puls\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/09 09:53
L10	239	((chemical adj (mechanical adj (polish\$4 or planar\$))) or "CMP") and (heat\$3 NEAR3 puls\$3) and heater	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/09 09:53

L11	222	((chemical adj (mechanical adj (polish\$4 or planar\$))) or "CMP") and (heat\$3 NEAR3 puls\$3) and heater and wafer and (film or layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/09 09:54
L12	222	((chemical adj (mechanical adj (polish\$4 or planar\$))) or "CMP") and (heat\$3 NEAR3 puls\$3) and heater and wafer and (film or layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 09:54
L13	172	((chemical adj (mechanical adj (polish\$4 or planar\$))) or "CMP") and (heat\$3 NEAR3 puls\$3) and heater and wafer and ((film or layer) NEAR4 thick\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 09:54
L14	74	((chemical adj (mechanical adj (polish\$4 or planar\$))) or "CMP") and (heat\$3 NEAR3 puls\$3) and heater and wafer and ((film or layer) NEAR4 thick\$) and ((temperature or thermal or heat) NEAR2 (sens\$3 or detect\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 09:56
L15	1076	((chemical adj (mechanical adj (polish\$4 or planar\$))) or "CMP") and ((temperature or thermal or heat) NEAR2 (sens\$3 or detect\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 09:57
L16	433	((chemical adj (mechanical adj (polish\$4 or planar\$))) or "CMP") and ((temperature or thermal or heat) NEAR2 (sens\$3 or detect\$3)) and puls\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 10:04
L17	339	((chemical adj (mechanical adj (polish\$4 or planar\$))) or "CMP") and ((temperature or thermal or heat) NEAR2 (sens\$3 or detect\$3)) and puls\$3 and thick\$ and (layer or film)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 10:17
L18	253	((chemical adj (mechanical adj (polish\$4 or planar\$))) or "CMP") and ((temperature or thermal or heat) NEAR2 (sens\$3 or detect\$3)) and puls\$3 and thick\$ and (layer or film) and (heat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 10:21

L19	124	((chemical adj (mechanical adj (polish\$4 or planar\$))) or "CMP") and ((temperature or thermal or heat) NEAR2 (sens\$3 or detect\$3)) and puls\$3 and thick\$ and (layer or film) and (heat\$3) and (temperature) and (radiation or ("IR" or infrared) or (infra-red) or (infra adj red)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 11:11
L20	344	356/630.ccls. and thick\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 11:25
L21	286	356/630.ccls. and thick\$ and (layer or coat\$4 or film)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 11:25
L22	118	356/630.ccls. and thick\$ and (layer or coat\$4 or film) and radiation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 11:26
L23	86	356/630.ccls. and thick\$ and (layer or coat\$4 or film) and radiation and (heat\$3 or thermal\$ or temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 12:00
L24	1	356/630.ccls. and thick\$ and (layer or coat\$4 or film) and radiation and (heat\$3 or thermal\$ or temperature) and "374"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 11:37
L25	6	356/630.ccls. and "374"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 11:37
L26	604	"CMP" and (thick\$ NEAR4 (layer or coat\$3 or film)) and radiation and ("IR" or infrared or (infra-red) or (infra adj red))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 12:01
L27	488	"CMP" and (thick\$ NEAR4 (layer or coat\$3 or film)) and radiation and ("IR" or infrared or (infra-red) or (infra adj red)) and (heats or heating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 12:10

L28	49	"CMP" and (thick\$ NEAR4 (layer or coat\$3 or film)) and radiation and ("IR" or infrared or (infra-red) or (infra adj red)) and (local\$ NEAR2 (heats or heating))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 12:43
L29	13	"CMP" and "374"/\$.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 12:12
L30	0	"chemical adj mechanical" and "374"/\$.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 12:12
L31	3	"chemical-mechanical" and "374"/\$.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 12:13
L32	406	374/57.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 12:30
L33	71	374/57.ccls. and thick\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 12:35
L35	121	374/7.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/09 12:36
L36	69	374/7.ccls. and (heats or heating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/09 12:36
L37	8	374/7.ccls. and ((heats or heating) NEAR3 local\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/09 12:36
L38	51	374/7.ccls. and (radiation or ("IR" or infrared or (infra-red) or (infra adj red)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 12:43

L39	42	374/7.ccls. and (radiation or ("IR" or infrared or (infra-red) or (infra adj red))) and thick\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 12:43
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L28	49	"CMP" and (thick\$ NEAR4 (layer or coat\$3 or film)) and radiation and ("IR" or infrared or (infra-red) or (infra adj red)) and (local\$ NEAR2 (heats or heating))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 12:11
L29	13	"CMP" and "374"/\$.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 12:12
L30	0	"chemical adj mechanical" and "374"/\$.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 12:12
L31	3	"chemical-mechanical" and "374"/\$.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 12:13
S2	4934	chemical adj (mechanical adj planarization)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/07 10:06
S3	137	(chemical adj (mechanical adj planarization)) adj system	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/07 10:10
S4	0	((chemical adj (mechanical adj planarization)) adj system) and (impulse adj heater)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/07 10:09
S5	1	((chemical adj (mechanical adj planarization)) adj system) and heater and computer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/07 10:09
S6	48	((chemical adj (mechanical adj planarization)) adj system) and thickness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/08 16:37
S7	37	((chemical adj (mechanical adj planarization)) adj system) and thickness and layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/07 10:11

S8	13	((chemical adj (mechanical adj planarization)) adj system) and (thickness NEAR layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/07 10:11
S9	0	((chemical adj (mechanical adj planarization)) adj system) and (measuring NEAR thickness)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/08 16:37
S10	5	((chemical adj (mechanical adj planarization)) adj system) and (measur\$ NEAR thickness)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/08 16:44
S11	1348	((chemical adj (mechanical adj planarization)) or "CMP") and (measur\$ NEAR thickness)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/09 09:52
S12	550	((chemical adj (mechanical adj planarization)) or "CMP") and (measur\$ NEAR thickness) and heat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/08 16:46
S13	101	((chemical adj (mechanical adj planarization)) or "CMP") and (measur\$ NEAR thickness) and heat\$5 and ((heat or thermal or temperature) NEAR (sens\$3 or detect\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/08 16:46
S14	64	((chemical adj (mechanical adj planarization)) or "CMP") and (measur\$ NEAR thickness) and (heater or heating) and ((heat or thermal or temperature) NEAR (sens\$3 or detect\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/08 17:11
S15	103	((chemical adj (mechanical adj planarization)) or "CMP") and (measur\$ NEAR thickness) and (heater or heating or heat) and ((heat or thermal or temperature) NEAR (sens\$3 or detect\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/08 16:47
S16	3	((chemical adj (mechanical adj planarization)) or "CMP") and (measur\$ NEAR thickness) and (heater or heating) and ((heat or thermal or temperature) NEAR (sens\$3 or detect\$4)) and ("IR" or (infra adj red) or (infra-red))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/08 17:12

S17	33	((chemical adj (mechanical adj planarization)) or "CMP") and (measur\$ NEAR thickness) and (heater or heating) and ((heat or thermal or temperature) NEAR (sens\$3 or detect\$4)) and ("IR" or (infra adj red) or (infra-red) or infrared)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/08 17:14
S18	121	374/7.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/08 18:17
S19	1082	374/121.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/08 17:15
S20	311	374/131.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/08 17:15
S21	1138	374/141.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/08 17:15
S22	677	374/45.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/08 17:16
S23	1579	451/5.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/08 17:16
S24	2995	451/41.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/08 17:16
S25	191	451/7.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/08 17:16

S26	95	374/7.ccls. and (thick\$ or layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/08 17:47
S27	270	374/121.ccls. and (thick\$ or layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/08 17:23
S29	161	374/131.ccls. and (thick\$ or layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/08 17:23
S30	255	374/141.ccls. and (thick\$ or layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/08 17:23
S31	195	374/45.ccls. and (thick\$ or layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/08 17:23
S32	16	374/7.ccls. and (thick\$ or layer) and (wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/08 17:47
S33	18	374/7.ccls. and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/08 17:50
S34	18	374/7.ccls. and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/08 17:50
S35	34	374/45.ccls. and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/08 17:50
S36	18	374/45.ccls. and wafer and thick\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/08 17:52

S37	24	374/141.ccls. and wafer and thick\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/08 18:02
S38	28	374/131.ccls. and wafer and thick\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/08 17:58
S39	27	374/141.ccls. and (layer NEAR2 thick\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/08 18:03
S40	561	"374"/\$.ccls. and (layer NEAR2 thick\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/08 18:03
S41	112	"374"/\$.ccls. and (layer NEAR2 thick\$) and (heater or heating) and (semiconductor or wafer) and (radiation or pyrometer or (infrared or ("IR") or (infra adj red) or (infra-red)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/08 18:06
S42	82	374/6.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/08 18:22
S43	246	374/5.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/08 18:22
S44	101	374/5.ccls. and thick\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/09 08:55